

Features

- Frequency: 33GHz~37GHz
- Power Gain: 15dB
- Psat: 38dBm
- P.A.E: 18%
- +22V @ 1.5A (Quiescent)
- Dimension: 3.65mm×2.55mm×0.10mm

Electrical Specification

(TA=+25°C, Vd=+22V, Vg=-1.8V)

Parameter	Min	Typ.	Max.	Unit
Frequency		33-37		GHz
Psat		38		dBm
Power Gain		15		dB
P.A.E		18		%
Dynamic Operating Current		1.5		A

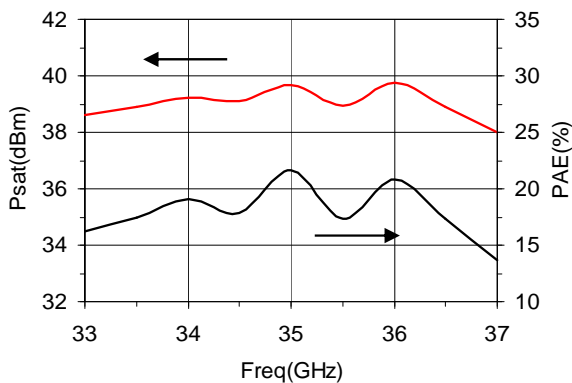
Note: 1) All chips have been 100% DC tested.
 2) Test Condition: Vd=+22V, Vg=-1.8V, P_{in}=24dBm, pulse width 100μs, duty cycle 2%.

Limited Rating Values

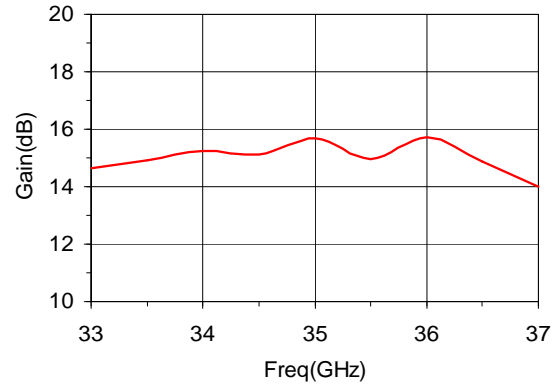
Vds	+24V
Vgs	-6V
Input CW Power	+30dBm
Channel Temperature	+175°C
Storage Temperature	-65°C ~ +150°C

Typical Testing Curves

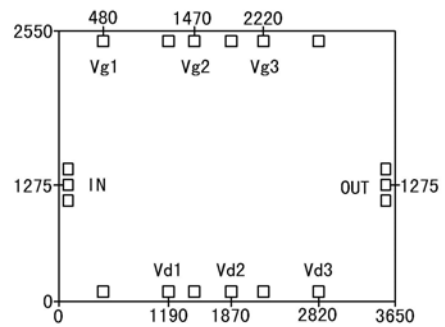
Psat/Efficiency vs. Frequency



Power Gain vs. Efficiency

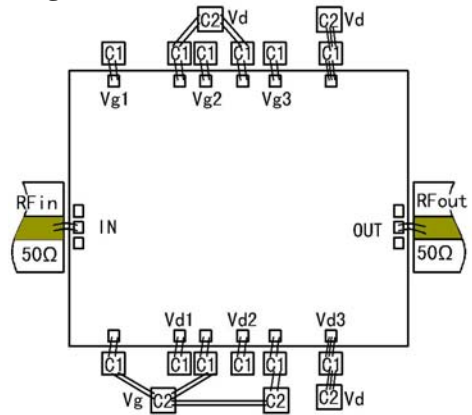


Dimension and Outline



Note: The unit is μm.
 Dimension of input and output pad: 100×120μm².
 Dimension of bias pad 120×120μm²

Assembly Diagram



Note: External capacitor C1:100pF, C2:1000pF

Attention

- 1) Two bonding wires are needed for input and output (diameter 25μm). Bonding wires shall not be longer than 500μm.
- 2) Bonding with 80/20 Au/Sn. Temperature should be lower than 300°C and time should be less than 30 seconds.
- 3) Blocking capacitors in Input/Output are already integrated.